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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	18MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	26
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 3.6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	28-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/p89lpc9301fdh-512

3. Ordering information

Table 1. Ordering information

Type number	Package		
	Name	Description	Version
P89LPC9301FDH	TSSOP28	plastic thin shrink small outline package; 28 leads; body width 4.4 mm	SOT361-1
P89LPC931A1FDH	TSSOP28	plastic thin shrink small outline package; 28 leads; body width 4.4 mm	SOT361-1

3.1 Ordering options

Table 2. Ordering options

Type number	Flash memory	Temperature range	Frequency
P89LPC9301FDH	4 kB	−40 °C to +85 °C	0 MHz to 18 MHz
P89LPC931A1FDH	8 kB	−40 °C to +85 °C	0 MHz to 18 MHz

Table 3. Pin description *…continued*

Symbol	Pin	Type	Description
P2.2/MOSI	13	I/O	**P2.2 —** Port 2 bit 2.
		I/O	**MOSI —** SPI master out slave in. When configured as master, this pin is output; when configured as slave, this pin is input.
P2.3/MISO	14	I/O	**P2.3 —** Port 2 bit 3.
		I/O	**MISO —** When configured as master, this pin is input, when configured as slave, this pin is output.
P2.4/$\overline{SS}$	15	I/O	**P2.4 —** Port 2 bit 4.
		I	**$\overline{SS}$ —** SPI Slave select.
P2.5/SPICLK	16	I/O	**P2.5 —** Port 2 bit 5.
		I/O	**SPICLK —** SPI clock. When configured as master, this pin is output; when configured as slave, this pin is input.
P2.6	27	I/O	**P2.6 —** Port 2 bit 6.
P2.7	28	I/O	**P2.7 —** Port 2 bit 7.
P3.0 to P3.1		I/O	**Port 3:** Port 3 is a 2-bit I/O port with a user-configurable output type. During reset Port 3 latches are configured in the input only mode with the internal pull-up disabled. The operation of Port 3 pins as inputs and outputs depends upon the port configuration selected. Each port pin is configured independently. Refer to Section 7.16.1 “Port configurations” and Table 10 “Static characteristics” for details. All pins have Schmitt trigger inputs. Port 3 also provides various special functions as described below:
P3.0/XTAL2/ CLKOUT	9	I/O	**P3.0 —** Port 3 bit 0.
		O	**XTAL2 —** Output from the oscillator amplifier (when a crystal oscillator option is selected via the flash configuration.
		O	**CLKOUT —** CPU clock divided by 2 when enabled via SFR bit (ENCLK -TRIM.6). It can be used if the CPU clock is the internal RC oscillator, watchdog oscillator or external clock input, except when XTAL1/XTAL2 are used to generate clock source for the RTC/system timer.
P3.1/XTAL1	8	I/O	**P3.1 —** Port 3 bit 1.
		I	**XTAL1 —** Input to the oscillator circuit and internal clock generator circuits (when selected via the flash configuration). It can be a port pin if internal RC oscillator or watchdog oscillator is used as the CPU clock source, **and** if XTAL1/XTAL2 are not used to generate the clock for the RTC/system timer.
V_{SS}	7	I	**Ground:** 0 V reference.
V_{DD}	21	I	**Power supply:** This is the power supply voltage for normal operation as well as Idle and Power-down modes.

[1] Input/output for P1.0 to P1.4, P1.6, P1.7. Input for P1.5.

Table 4. Special function registers

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
	Bit address		**E7**	**E6**	**E5**	**E4**	**E3**	**E2**	**E1**	**E0**		
ACC*	Accumulator	E0H									00	0000 0000
AUXR1	Auxiliary function register	A2H	CLKLP	EBRR	ENT1	ENT0	SRST	0	-	DPS	00	0000 00x0
	Bit address		**F7**	**F6**	**F5**	**F4**	**F3**	**F2**	**F1**	**F0**		
B*	B register	F0H									00	0000 0000
BRGR0[2]	Baud rate generator 0 rate low	BEH									00	0000 0000
BRGR1[2]	Baud rate generator 0 rate high	BFH									00	0000 0000
BRGCON	Baud rate generator 0 control	BDH	-	-	-	-	-	-	SBRGS	BRGEN	00[2]	xxxx xx00
CMP1	Comparator 1 control register	ACH	-	-	CE1	CP1	CN1	OE1	CO1	CMF1	00[1]	xx00 0000
CMP2	Comparator 2 control register	ADH	-	-	CE2	CP2	CN2	OE2	CO2	CMF2	00[1]	xx00 0000
DIVM	CPU clock divide-by-M control	95H									00	0000 0000
DPTR	Data pointer (2 bytes)											
DPH	Data pointer high	83H									00	0000 0000
DPL	Data pointer low	82H									00	0000 0000
FMADRH	Program flash address high	E7H									00	0000 0000
FMADRL	Program flash address low	E6H									00	0000 0000

Table 4. Special function registers *…continued*

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
P1M2	Port 1 output mode 2	92H	(P1M2.7)	(P1M2.6)	-	(P1M2.4)	(P1M2.3)	(P1M2.2)	(P1M2.1)	(P1M2.0)	00[1]	00x0 xx00
P2M1	Port 2 output mode 1	A4H	(P2M1.7)	(P2M1.6)	(P2M1.5)	(P2M1.4)	(P2M1.3)	(P2M1.2)	(P2M1.1)	(P2M1.0)	FF[1]	1111 1111
P2M2	Port 2 output mode 2	A5H	(P2M2.7)	(P2M2.6)	(P2M2.5)	(P2M2.4)	(P2M2.3)	(P2M2.2)	(P2M2.1)	(P2M2.0)	00[1]	0000 0000
P3M1	Port 3 output mode 1	B1H	-	-	-	-	-	-	(P3M1.1)	(P3M1.0)	03[1]	xxxx xx11
P3M2	Port 3 output mode 2	B2H	-	-	-	-	-	-	(P3M2.1)	(P3M2.0)	00[1]	xxxx xx00
PCON	Power control register	87H	SMOD1	SMOD0	-	BOI	GF1	GF0	PMOD1	PMOD0	00	0000 0000
PCONA	Power control register A	B5H	RTCPD	-	VCPD	-	I2PD	SPPD	SPD	-	00[1]	0000 0000
	Bit address		**D7**	**D6**	**D5**	**D4**	**D3**	**D2**	**D1**	**D0**		
PSW*	Program status word	D0H	CY	AC	F0	RS1	RS0	OV	F1	P	00	0000 0000
PT0AD	Port 0 digital input disable	F6H	-	-	PT0AD.5	PT0AD.4	PT0AD.3	PT0AD.2	PT0AD.1	-	00	xx00 000x
RSTSRC	Reset source register	DFH	-	BOIF	BOF	POF	R_BK	R_WD	R_SF	R_EX	[3]	
RTCCON	RTC control	D1H	RTCF	RTCS1	RTCS0	-	-	-	ERTC	RTCEN	60[1][6]	011x xx00
RTCH	RTC register high	D2H									00[6]	0000 0000
RTCL	RTC register low	D3H									00[6]	0000 0000
SADDR	Serial port address register	A9H									00	0000 0000
SADEN	Serial port address enable	B9H									00	0000 0000
SBUF	Serial Port data buffer register	99H									xx	xxxx xxxx

Table 4. Special function registers *…continued*

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
	Bit address		**9F**	**9E**	**9D**	**9C**	**9B**	**9A**	**99**	**98**		
SCON*	Serial port control	98H	SM0/FE	SM1	SM2	REN	TB8	RB8	TI	RI	00	0000 0000
SSTAT	Serial port extended status register	BAH	DBMOD	INTLO	CIDIS	DBISEL	FE	BR	OE	STINT	00	0000 0000
SP	Stack pointer	81H									07	0000 0111
SPCTL	SPI control register	E2H	SSIG	SPEN	DORD	MSTR	CPOL	CPHA	SPR1	SPR0	04	0000 0100
SPSTAT	SPI status register	E1H	SPIF	WCOL	-	-	-	-	-	-	00	00xx xxxx
SPDAT	SPI data register	E3H									00	0000 0000
TAMOD	Timer 0 and 1 auxiliary mode	8FH	-	-	-	T1M2	-	-	-	T0M2	00	xxx0 xxx0
	Bit address		**8F**	**8E**	**8D**	**8C**	**8B**	**8A**	**89**	**88**		
TCON*	Timer 0 and 1 control	88H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0	00	0000 0000
TH0	Timer 0 high	8CH									00	0000 0000
TH1	Timer 1 high	8DH									00	0000 0000
TL0	Timer 0 low	8AH									00	0000 0000
TL1	Timer 1 low	8BH									00	0000 0000
TMOD	Timer 0 and 1 mode	89H	T1GATE	T1C/T	T1M1	T1M0	T0GATE	T0C/T	T0M1	T0M0	00	0000 0000
TRIM	Internal oscillator trim register	96H	RCCLK	ENCLK	TRIM.5	TRIM.4	TRIM.3	TRIM.2	TRIM.1	TRIM.0	[5][6]	
WDCON	Watchdog control register	A7H	PRE2	PRE1	PRE0	-	-	WDRUN	WDTOF	WDCLK	[4][6]	

Table 4. Special function registers *…continued*

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
WDL	Watchdog load	C1H									FF	1111 1111
WFEED1	Watchdog feed 1	C2H										
WFEED2	Watchdog feed 2	C3H										

[1] All ports are in input only (high-impedance) state after power-up.

[2] BRGR1 and BRGR0 must only be written if BRGEN in BRGCON SFR is logic 0. If any are written while BRGEN = 1, the result is unpredictable.

[3] The RSTSRC register reflects the cause of the P89LPC9301/931A1 reset except BOIF bit. Upon a power-up reset, all reset source flags are cleared except POF and BOF; the power-on reset value is x011 0000.

[4] After reset, the value is 1110 01x1, i.e., PRE2 to PRE0 are all logic 1, WDRUN = 1 and WDCLK = 1. WDTOF bit is logic 1 after watchdog reset and is logic 0 after power-on reset. Other resets will not affect WDTOF.

[5] On power-on reset and watchdog reset, the TRIM SFR is initialized with a factory preprogrammed value. Other resets will not cause initialization of the TRIM register.

[6] The only reset sources that affect these SFRs are power-on reset and watchdog reset.

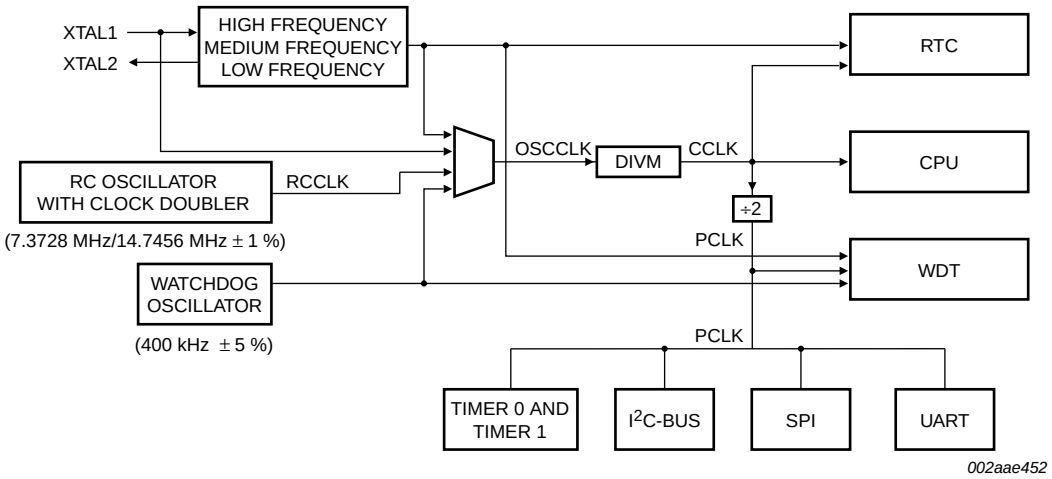

Fig 4. Block diagram of oscillator control

7.10 CCLK wake-up delay

The P89LPC9301/931A1 has an internal wake-up timer that delays the clock until it stabilizes depending on the clock source used. If the clock source is any of the three crystal selections (low, medium and high frequencies) the delay is 1024 OSCCLK cycles plus 60 μs to 100 μs. If the clock source is the internal RC oscillator, the delay is 200 μs to 300 μs. If the clock source is watchdog oscillator or external clock, the delay is 32 OSCCLK cycles.

7.11 CCLK modification: DIVM register

The OSCCLK frequency can be divided down up to 510 times by configuring a dividing register, DIVM, to generate CCLK. This feature makes it possible to temporarily run the CPU at a lower rate, reducing power consumption. By dividing the clock, the CPU can retain the ability to respond to events that would not exit Idle mode by executing its normal program at a lower rate. This can also allow bypassing the oscillator start-up time in cases where Power-down mode would otherwise be used. The value of DIVM may be changed by the program at any time without interrupting code execution.

7.12 Low power select

The P89LPC9301/931A1 is designed to run at 18 MHz (CCLK) maximum. However, if CCLK is 8 MHz or slower, the CLKLP SFR bit (AUXR1.7) can be set to logic 1 to lower the power consumption further. On any reset, CLKLP is logic 0 allowing highest performance access. This bit can then be set in software if CCLK is running at 8 MHz or slower.

7.17.1 Brownout detection

The brownout detect function determines if the power supply voltage drops below a certain level. Enhanced brownout detection has 3 independent functions: BOD reset, BOD interrupt and BOD FLASH.

BOD reset is always on except in total Power-down mode. It could not be disabled in software. BOD interrupt may be enabled or disabled in software. BOD FLASH is always on, except in Power-down modes and could not be disabled in software.

BOD reset and BOD interrupt, each has four trip voltage levels. BOE1 bit (UCFG1.5) and BOE0 bit (UCFG1.3) are used as trip point configuration bits of BOD reset. BOICFG1 bit and BOICFG0 bit in register BODCFG are used as trip point configuration bits of BOD interrupt. BOD reset voltage should be lower than BOD interrupt trip point. BOD FLASH is used for flash programming/erase protection and has only 1 trip voltage of 2.4 V. Please refer to *P89LPC9301/931A1 User manual* for detail configurations.

If brownout detection is enabled the brownout condition occurs when V_{DD} falls below the brownout trip voltage and is negated when V_{DD} rises above the brownout trip voltage.

For correct activation of brownout detect, the V_{DD} rise and fall times must be observed. Please see Table 10 “Static characteristics” for specifications.

7.17.2 Power-on detection

The Power-on detect has a function similar to the brownout detect, but is designed to work as power comes up initially, before the power supply voltage reaches a level where brownout detect can work. The POF flag in the RSTSRC register is set to indicate an initial power-up condition. The POF flag will remain set until cleared by software.

7.18 Power reduction modes

The P89LPC9301/931A1 supports three different power reduction modes. These modes are Idle mode, Power-down mode, and total Power-down mode.

7.18.1 Idle mode

Idle mode leaves peripherals running in order to allow them to activate the processor when an interrupt is generated. Any enabled interrupt source or reset may terminate Idle mode.

7.18.2 Power-down mode

The Power-down mode stops the oscillator in order to minimize power consumption. The P89LPC9301/931A1 exits Power-down mode via any reset, or certain interrupts. In Power-down mode, the power supply voltage may be reduced to the data retention supply voltage V_{DDR}. This retains the RAM contents at the point where Power-down mode was entered. SFR contents are not guaranteed after V_{DD} has been lowered to V_{DDR}, therefore it is highly recommended to wake-up the processor via reset in this case. V_{DD} must be raised to within the operating range before the Power-down mode is exited.

Some chip functions continue to operate and draw power during Power-down mode, increasing the total power used during power-down. These include: Brownout detect, watchdog timer, comparators (note that comparators can be powered down separately), and RTC/system timer. The internal RC oscillator is disabled unless both the RC oscillator has been selected as the system clock and the RTC is enabled.

7.18.3 Total Power-down mode

This is the same as Power-down mode except that the brownout detection circuitry and the voltage comparators are also disabled to conserve additional power. The internal RC oscillator is disabled unless both the RC oscillator has been selected as the system clock **and** the RTC is enabled. If the internal RC oscillator is used to clock the RTC during power-down, there will be high power consumption. Please use an external low frequency clock to achieve low power with the RTC running during power-down.

7.19 Reset

The P1.5/$\overline{\text{RST}}$ pin can function as either a LOW-active reset input or as a digital input, P1.5. The Reset Pin Enable (RPE) bit in UCFG1, when set to logic 1, enables the external reset input function on P1.5. When cleared, P1.5 may be used as an input pin.

Remark: During a power-up sequence, the RPE selection is overridden and this pin always functions as a reset input. **An external circuit connected to this pin should not hold this pin LOW during a power-on sequence as this will keep the device in reset.** After power-up this pin will function as defined by the RPE bit. Only a power-up reset will temporarily override the selection defined by RPE bit. Other sources of reset will not override the RPE bit. When this pin functions as a reset input, an internal pull-up resistance is connected (see Table 10 “Static characteristics”).

Note: During a power cycle, V_{DD} must fall below V_{POR} before power is reapplied, in order to ensure a power-on reset (see Table 10 “Static characteristics”).

Reset can be triggered from the following sources:

- External reset pin (during power-up or if user configured via UCFG1)
- Power-on detect
- Brownout detect
- Watchdog timer
- Software reset
- UART break character detect reset

For every reset source, there is a flag in the Reset Register, RSTSRC. The user can read this register to determine the most recent reset source. These flag bits can be cleared in software by writing a logic 0 to the corresponding bit. More than one flag bit may be set:

- During a power-on reset, both POF and BOF are set but the other flag bits are cleared.
- A Watchdog reset is similar to a power-on reset, both POF and BOF are set but the other flag bits are cleared.
- For any other reset, previously set flag bits that have not been cleared will remain set.

7.19.1 Reset vector

Following reset, the P89LPC9301/931A1 will fetch instructions from either address 0000H or the Boot address. The Boot address is formed by using the boot vector as the high byte of the address and the low byte of the address = 00H.

The boot address will be used if a UART break reset occurs, or the non-volatile boot status bit (BOOTSTAT.0) = 1, or the device is forced into ISP mode during power-on (see *P89LPC9301/931A1 User manual*). Otherwise, instructions will be fetched from address 0000H.

7.20 Timers/counters 0 and 1

The P89LPC9301/931A1 has two general purpose counter/timers which are upward compatible with the standard 80C51 Timer 0 and Timer 1. Both can be configured to operate either as timers or event counters. An option to automatically toggle the T0 and/or T1 pins upon timer overflow has been added.

In the 'Timer' function, the register is incremented every machine cycle.

In the 'Counter' function, the register is incremented in response to a 1-to-0 transition at its corresponding external input pin, T0 or T1. In this function, the external input is sampled once during every machine cycle.

Timer 0 and Timer 1 have five operating modes (Modes 0, 1, 2, 3 and 6). Modes 0, 1, 2 and 6 are the same for both Timers/Counters. Mode 3 is different.

7.20.1 Mode 0

Putting either Timer into Mode 0 makes it look like an 8048 Timer, which is an 8-bit Counter with a divide-by-32 prescaler. In this mode, the Timer register is configured as a 13-bit register. Mode 0 operation is the same for Timer 0 and Timer 1.

7.20.2 Mode 1

Mode 1 is the same as Mode 0, except that all 16 bits of the timer register are used.

7.20.3 Mode 2

Mode 2 configures the Timer register as an 8-bit Counter with automatic reload. Mode 2 operation is the same for Timer 0 and Timer 1.

7.20.4 Mode 3

When Timer 1 is in Mode 3 it is stopped. Timer 0 in Mode 3 forms two separate 8-bit counters and is provided for applications that require an extra 8-bit timer. When Timer 1 is in Mode 3 it can still be used by the serial port as a baud rate generator.

7.20.5 Mode 6

In this mode, the corresponding timer can be changed to a PWM with a full period of 256 timer clocks.

7.20.6 Timer overflow toggle output

Timers 0 and 1 can be configured to automatically toggle a port output whenever a timer overflow occurs. The same device pins that are used for the T0 and T1 count inputs are also used for the timer toggle outputs. The port outputs will be a logic 1 prior to the first timer overflow when this mode is turned on.

7.21 RTC/system timer

The P89LPC9301/931A1 has a simple RTC that allows a user to continue running an accurate timer while the rest of the device is powered down. The RTC can be a wake-up or an interrupt source. The RTC is a 23-bit down counter comprised of a 7-bit prescaler and a 16-bit loadable down counter. When it reaches all logic 0s, the counter will be reloaded again and the RTCF flag will be set. The clock source for this counter can be either the CPU clock (CCLK) or the XTAL oscillator. Only power-on reset and watchdog reset will reset the RTC and its associated SFRs to the default state.

The 16-bit loadable counter portion of the RTC is readable by reading the RTCDATL and RTCDATH registers.

7.22 UART

The P89LPC9301/931A1 has an enhanced UART that is compatible with the conventional 80C51 UART except that Timer 2 overflow cannot be used as a baud rate source. The P89LPC9301/931A1 does include an independent baud rate generator. The baud rate can be selected from the oscillator (divided by a constant), Timer 1 overflow, or the independent baud rate generator. In addition to the baud rate generation, enhancements over the standard 80C51 UART include Framing Error detection, automatic address recognition, selectable double buffering and several interrupt options. The UART can be operated in four modes: shift register, 8-bit UART, 9-bit UART, and CPU clock/32 or CPU clock/16.

7.22.1 Mode 0

Serial data enters and exits through RXD. TXD outputs the shift clock. 8 bits are transmitted or received, LSB first. The baud rate is fixed at $\frac{1}{16}$ of the CPU clock frequency.

7.22.2 Mode 1

10 bits are transmitted (through TXD) or received (through RXD): a start bit (logic 0), 8 data bits (LSB first), and a stop bit (logic 1). When data is received, the stop bit is stored in RB8 in special function register SCON. The baud rate is variable and is determined by the Timer 1 overflow rate or the baud rate generator (described in Section 7.22.5 “Baud rate generator and selection”).

7.22.3 Mode 2

11 bits are transmitted (through TXD) or received (through RXD): start bit (logic 0), 8 data bits (LSB first), a programmable 9th data bit, and a stop bit (logic 1). When data is transmitted, the 9th data bit (TB8 in SCON) can be assigned the value of logic 0 or logic 1. Or, for example, the parity bit (P, in the PSW) could be moved into TB8. When data is received, the 9th data bit goes into RB8 in special function register SCON, while the stop bit is not saved. The baud rate is programmable to either $\frac{1}{16}$ or $\frac{1}{32}$ of the CPU clock frequency, as determined by the SMOD1 bit in PCON.

7.24.1 Typical SPI configurations

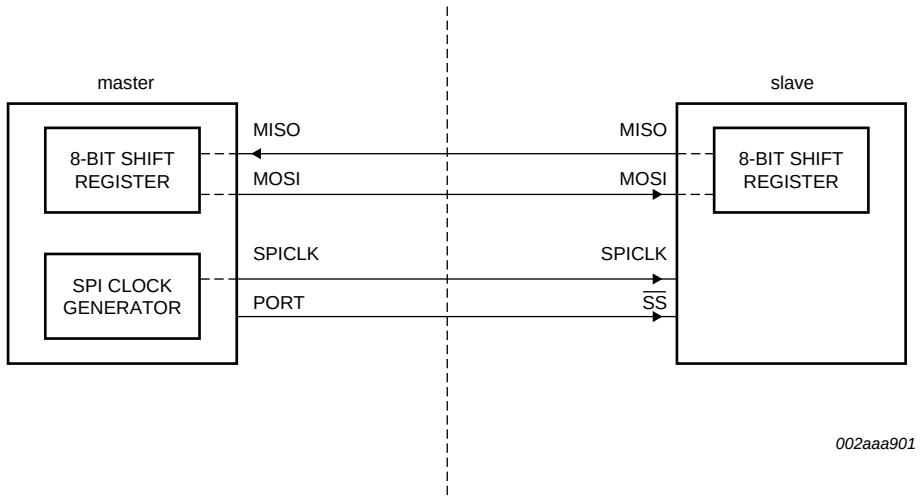

Fig 10. SPI single master single slave configuration

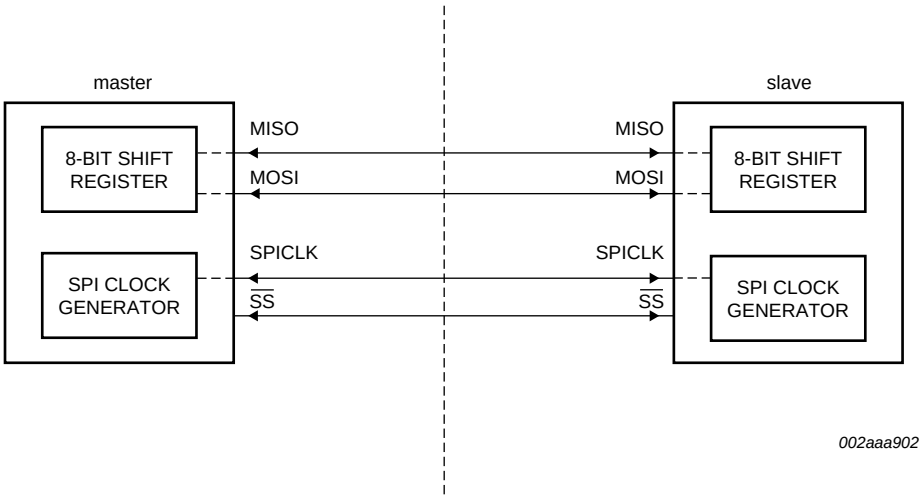

Fig 11. SPI dual device configuration, where either can be a master or a slave

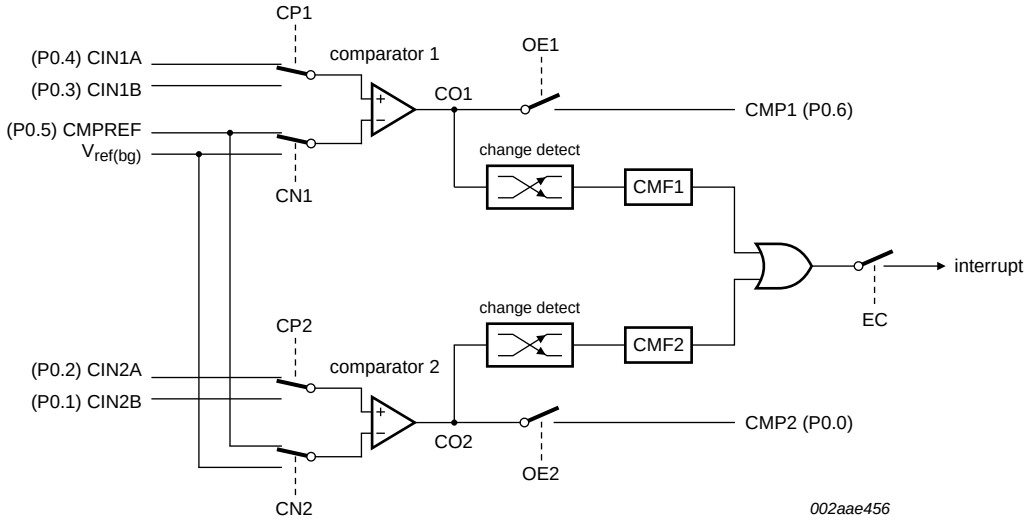

Fig 13. Comparator input and output connections

7.25.1 Internal reference voltage

An internal reference voltage generator may supply a default reference when a single comparator input pin is used. The value of the internal reference voltage, referred to as $V_{ref(bg)}$, is 1.23 V $\pm$ 10 %.

7.25.2 Comparator interrupt

Each comparator has an interrupt flag contained in its configuration register. This flag is set whenever the comparator output changes state. The flag may be polled by software or may be used to generate an interrupt. The two comparators use one common interrupt vector. If both comparators enable interrupts, after entering the interrupt service routine, the user needs to read the flags to determine which comparator caused the interrupt.

7.25.3 Comparators and power reduction modes

Either or both comparators may remain enabled when Power-down or Idle mode is activated, but both comparators are disabled automatically in Total Power-down mode.

If a comparator interrupt is enabled (except in Total Power-down mode), a change of the comparator output state will generate an interrupt and wake-up the processor. If the comparator output to a pin is enabled, the pin should be configured in the push-pull mode in order to obtain fast switching times while in Power-down mode. The reason is that with the **oscillator** stopped, the temporary strong pull-up that normally occurs during switching on a quasi-bidirectional port pin does not take place.

Comparators consume power in Power-down and Idle modes, as well as in the normal operating mode. This fact should be taken into account when system power consumption is an issue. To minimize power consumption, the user can disable the comparators via PCONA.5, or put the device in Total Power-down mode.

optimize the erase and programming mechanisms. The P89LPC9301/931A1 uses V_{DD} as the supply voltage to perform the Program/Erase algorithms. When voltage supply is lower than 2.4 V, the BOD FLASH is tripped and flash erase/program is blocked.

7.29.2 Features

- Programming and erase over the full operating voltage range.
- Byte erase allows code memory to be used for data storage.
- Read/Programming/Erase using ISP/IAP/ICP.
- Internal fixed boot ROM, containing low-level IAP routines available to user code.
- Default loader providing ISP via the serial port, located in upper end of user program memory.
- Boot vector allows user-provided flash loader code to reside anywhere in the flash memory space, providing flexibility to the user.
- Any flash program/erase operation in 2 ms.
- Programming with industry-standard commercial programmers.
- Programmable security for the code in the flash for each sector.
- 100,000 typical erase/program cycles for each byte.
- 10 year minimum data retention.

7.29.3 Flash organization

The program memory consists of four/eight 1 kB sectors on the P89LPC9301/931A1 devices. Each sector can be further divided into 64-byte pages. In addition to sector erase, page erase, and byte erase, a 64-byte page register is included which allows from 1 byte to 64 bytes of a given page to be programmed at the same time, substantially reducing overall programming time.

7.29.4 Using flash as data storage

The flash code memory array of this device supports individual byte erasing and programming. Any byte in the code memory array may be read using the MOVC instruction, provided that the sector containing the byte has not been secured (a MOVC instruction is not allowed to read code memory contents of a secured sector). Thus any byte in a non-secured sector may be used for non-volatile data storage.

7.29.5 Flash programming and erasing

Four different methods of erasing or programming of the flash are available. The flash may be programmed or erased in the end-user application (IAP) under control of the application's firmware. Another option is to use the ICP mechanism. This ICP system provides for programming through a serial clock/serial data interface. As shipped from the factory, the upper 512 bytes of user code space contains a serial ISP routine allowing for the device to be programmed in circuit through the serial port. The flash may also be programmed or erased using a commercially available EPROM programmer which supports this device. This device does not provide for direct verification of code memory contents. Instead, this device provides a 32-bit CRC result on either a sector or the entire user code space.

Remark: When voltage supply is lower than 2.4 V, the BOD FLASH is tripped and flash erase/program is blocked.

Table 10. Static characteristics *…continued*
V_{DD} = 2.4 V to 3.6 V unless otherwise specified.
T_{amb} = −40 °C to +85 °C for industrial applications, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
I_{THL}	HIGH-LOW transition current	all ports; V_I = 1.5 V at V_{DD} = 3.6 V	[11]	−30	-	−450	μA
$R_{RST\_N(int)}$	internal pull-up resistance on pin $\overline{RST}$	pin $\overline{RST}$		10	-	30	kΩ
$V_{ref(bg)}$	band gap reference voltage			1.11	1.23	1.34	V
TC_{bg}	band gap temperature coefficient			-	10	20	ppm/°C

[1] Typical ratings are not guaranteed. The values listed are at room temperature, 3 V.

[2] The $I_{DD(oper)}$ specification is measured using an external clock with code while(1) {} executed from on-chip flash.

[3] The $I_{DD(idle)}$ specification is measured using an external clock with no active peripherals, with the following functions disabled: real-time clock and watchdog timer.

[4] The $I_{DD(pd)}$ specification is measured using internal RC oscillator with the following functions disabled: comparators, real-time clock, and watchdog timer.

[5] The $I_{DD(tpd)}$ specification is measured using an external clock with the following functions disabled: comparators, real-time clock, brownout detect, and watchdog timer.

[6] See Section 8 “Limiting values” for steady state (non-transient) limits on I_{OL} or I_{OH}. If I_{OL}/I_{OH} exceeds the test condition, V_{OL}/V_{OH} may exceed the related specification.

[7] This specification can be applied to pins which have A/D input or analog comparator input functions when the pin is not being used for those analog functions. When the pin is being used as an analog input pin, the maximum voltage on the pin must be limited to 4.0 V with respect to V_{SS}.

[8] Pin capacitance is characterized but not tested.

[9] Measured with port in quasi-bidirectional mode.

[10] Measured with port in high-impedance mode.

[11] Port pins source a transition current when used in quasi-bidirectional mode and externally driven from logic 1 to logic 0. This current is highest when V_I is approximately 2 V.

10. Dynamic characteristics

Table 12. Dynamic characteristics (12 MHz)

V_{DD} = 2.4 V to 3.6 V unless otherwise specified.

T_{amb} = −40 °C to +85 °C for industrial applications, unless otherwise specified.[1][2]

Symbol	Parameter	Conditions	Variable clock		f_{osc} = 12 MHz		Unit
			Min	Max	Min	Max	
$f_{osc(RC)}$	internal RC oscillator frequency	nominal f = 7.3728 MHz trimmed to ±1 % at T_{amb} = 25 °C; clock doubler option = OFF (default)	7.189	7.557	7.189	7.557	MHz
		nominal f = 14.7456 MHz; clock doubler option = ON, V_{DD} = 2.7 V to 3.6 V	14.378	15.114	14.378	15.114	MHz
$f_{osc(WD)}$	internal watchdog oscillator frequency	T_{amb} = 25 °C	380	420	380	420	kHz
f_{osc}	oscillator frequency		0	12	-	-	MHz
$T_{cy(clk)}$	clock cycle time	see Figure 32	83	-	-	-	ns
f_{CLKLP}	low-power select clock frequency		0	8	-	-	MHz
Glitch filter							
t_{gr}	glitch rejection time	P1.5/$\overline{\text{RST}}$ pin	-	50	-	50	ns
		any pin except P1.5/$\overline{\text{RST}}$	-	15	-	15	ns
t_{sa}	signal acceptance time	P1.5/$\overline{\text{RST}}$ pin	125	-	125	-	ns
		any pin except P1.5/$\overline{\text{RST}}$	50	-	50	-	ns
External clock							
t_{CHCX}	clock HIGH time	see Figure 32	33	$T_{cy(clk)} - t_{CLCX}$	33	-	ns
t_{CLCX}	clock LOW time	see Figure 32	33	$T_{cy(clk)} - t_{CHCX}$	33	-	ns
t_{CLCH}	clock rise time	see Figure 32	-	8	-	8	ns
t_{CHCL}	clock fall time	see Figure 32	-	8	-	8	ns
Shift register (UART mode 0)							
T_{XLXL}	serial port clock cycle time	see Figure 31	$16T_{cy(clk)}$	-	1333	-	ns
t_{QVXH}	output data set-up to clock rising edge time	see Figure 31	$13T_{cy(clk)}$	-	1083	-	ns
t_{XHQX}	output data hold after clock rising edge time	see Figure 31	-	$T_{cy(clk)}$ + 20	-	103	ns
t_{XHDX}	input data hold after clock rising edge time	see Figure 31	-	0	-	0	ns
t_{XHDV}	input data valid to clock rising edge time	see Figure 31	150	-	150	-	ns
SPI interface							
f_{SPI}	SPI operating frequency						
	slave		0	$^{CCLK}/_{6}$	0	2.0	MHz
	master		-	$^{CCLK}/_{4}$	-	3.0	MHz

Table 12. Dynamic characteristics (12 MHz) *…continued*
V_{DD} = 2.4 V to 3.6 V unless otherwise specified.
T_{amb} = −40 °C to +85 °C for industrial applications, unless otherwise specified.[1][2]

Symbol	Parameter	Conditions	Variable clock		f_{osc} = 12 MHz		Unit
			Min	Max	Min	Max	
T_{SPICYC}	SPI cycle time	see Figure 33, 34, 35, 36					
	slave		$^{6}/_{CCLK}$	-	500	-	ns
	master		$^{4}/_{CCLK}$	-	333	-	ns
$t_{SPILEAD}$	SPI enable lead time	see Figure 35, 36					
	slave		250	-	250	-	ns
t_{SPILAG}	SPI enable lag time	see Figure 35, 36					
	slave		250	-	250	-	ns
$t_{SPICLKH}$	SPICLK HIGH time	see Figure 33, 34, 35, 36					
	master		$^{2}/_{CCLK}$	-	165	-	ns
	slave		$^{3}/_{CCLK}$	-	250	-	ns
$t_{SPICLKL}$	SPICLK LOW time	see Figure 33, 34, 35, 36					
	master		$^{2}/_{CCLK}$	-	165	-	ns
	slave		$^{3}/_{CCLK}$	-	250	-	ns
t_{SPIDSU}	SPI data set-up time	see Figure 33, 34, 35, 36	100	-	100	-	ns
	master or slave						
t_{SPIDH}	SPI data hold time	see Figure 33, 34, 35, 36	100	-	100	-	ns
	master or slave						
t_{SPIA}	SPI access time	see Figure 35, 36					
	slave		0	120	0	120	ns
t_{SPIDIS}	SPI disable time	see Figure 35, 36					
	slave		0	240	-	240	ns
t_{SPIDV}	SPI enable to output data valid time	see Figure 33, 34, 35, 36					
	slave		-	240	-	240	ns
	master		-	167	-	167	ns
t_{SPIOH}	SPI output data hold time	see Figure 33, 34, 35, 36	0	-	0	-	ns
t_{SPIR}	SPI rise time	see Figure 33, 34, 35, 36					
	SPI outputs (SPICLK, MOSI, MISO)		-	100	-	100	ns
	SPI inputs (SPICLK, MOSI, MISO, $\overline{SS}$)		-	2000	-	2000	ns
t_{SPIF}	SPI fall time	see Figure 33, 34, 35, 36					
	SPI outputs (SPICLK, MOSI, MISO)		-	100	-	100	ns
	SPI inputs (SPICLK, MOSI, MISO, $\overline{SS}$)		-	2000	-	2000	ns

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Parts are tested to 2 MHz, but are guaranteed to operate down to 0 Hz.

Table 13. Dynamic characteristics (18 MHz)

V_{DD} = 3.0 V to 3.6 V unless otherwise specified.

T_{amb} = −40 °C to +85 °C for industrial applications, unless otherwise specified.[1][2]

Symbol	Parameter	Conditions	Variable clock		f_{osc} = 18 MHz		Unit
			Min	Max	Min	Max	
$f_{osc(RC)}$	internal RC oscillator frequency	nominal f = 7.3728 MHz trimmed to ±1 % at T_{amb} = 25 °C; clock doubler option = OFF (default)	7.189	7.557	7.189	7.557	MHz
		nominal f = 14.7456 MHz; clock doubler option = ON	14.378	15.114	14.378	15.114	MHz
$f_{osc(WD)}$	internal watchdog oscillator frequency	T_{amb} = 25 °C	380	420	380	420	kHz
f_{osc}	oscillator frequency		0	18	-	-	MHz
$T_{cy(clk)}$	clock cycle time	see Figure 32	55	-	-	-	ns
f_{CLKLP}	low-power select clock frequency		0	8	-	-	MHz
Glitch filter							
t_{gr}	glitch rejection time	P1.5/$\overline{RST}$ pin	-	50	-	50	ns
		any pin except P1.5/$\overline{RST}$	-	15	-	15	ns
t_{sa}	signal acceptance time	P1.5/$\overline{RST}$ pin	125	-	125	-	ns
		any pin except P1.5/$\overline{RST}$	50	-	50	-	ns
External clock							
t_{CHCX}	clock HIGH time	see Figure 32	22	$T_{cy(clk)} - t_{CLCX}$	22	-	ns
t_{CLCX}	clock LOW time	see Figure 32	22	$T_{cy(clk)} - t_{CHCX}$	22	-	ns
t_{CLCH}	clock rise time	see Figure 32	-	5	-	5	ns
t_{CHCL}	clock fall time	see Figure 32	-	5	-	5	ns
Shift register (UART mode 0)							
T_{XLXL}	serial port clock cycle time	see Figure 31	$16T_{cy(clk)}$	-	888	-	ns
t_{QVXH}	output data set-up to clock rising edge time	see Figure 31	$13T_{cy(clk)}$	-	722	-	ns
t_{XHQX}	output data hold after clock rising edge time	see Figure 31	-	$T_{cy(clk)}$ + 20	-	75	ns
t_{XHDX}	input data hold after clock rising edge time	see Figure 31	-	0	-	0	ns
t_{XHDV}	input data valid to clock rising edge time	see Figure 31	150	-	150	-	ns
SPI interface							
f_{SPI}	SPI operating frequency						
	slave		0	$^{CCLK}/_{6}$	0	3.0	MHz
	master		-	$^{CCLK}/_{4}$	-	4.5	MHz
T_{SPICYC}	SPI cycle time	see Figure 33, 34, 35, 36					
	slave		$^{6}/_{CCLK}$	-	333	-	ns
	master		$^{4}/_{CCLK}$	-	222	-	ns

10.1 Waveforms

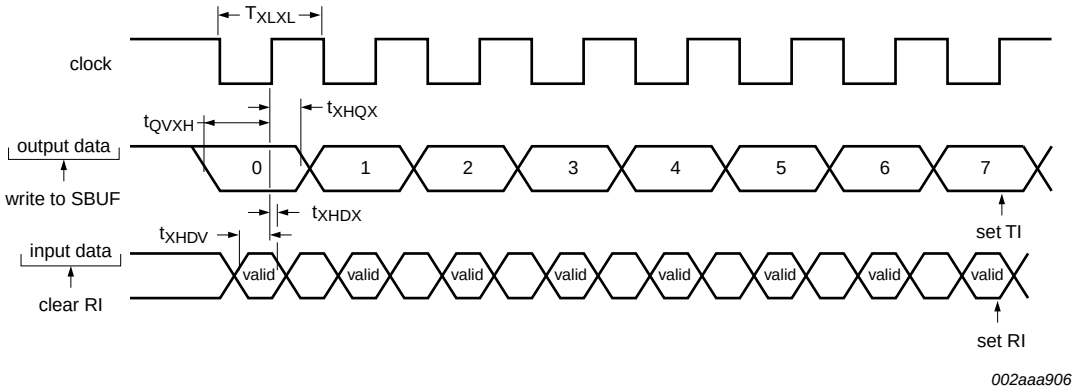

Fig 31. Shift register mode timing

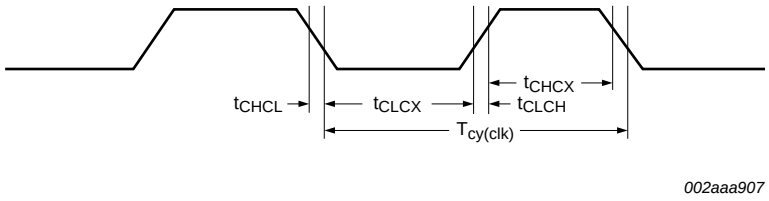

Fig 32. External clock timing (with an amplitude of at least $V_{i(RMS)}$ = 200 mV)

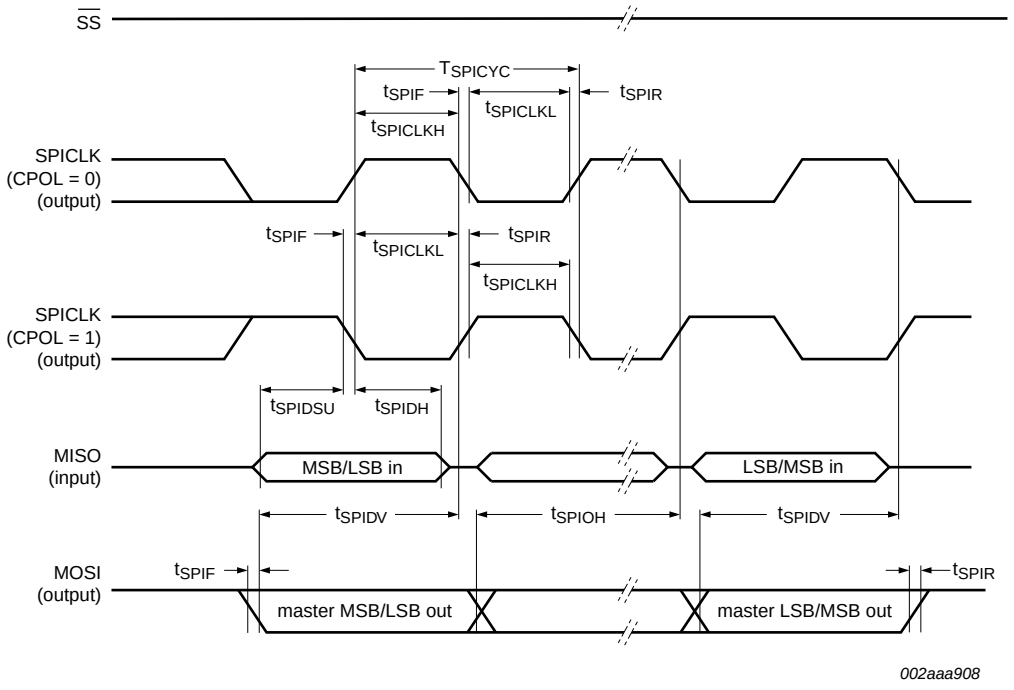

Fig 33. SPI master timing (CPHA = 0)

15. Legal information

15.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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